Kulicke & Soffa Joins High-Density Fan-Out Wafer Level Packaging Consortium

SINGAPORE--(BUSINESS WIRE)--Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") today announced they are joining A*STAR's Institute of Microelectronics (IME)'s High-Density Fan-Out Wafer Level Packaging (FOWLP) consortium, together with other major industry players. Through the collaboration, K&S is confident that with the combined experience and knowledge, the consortium will extend FOWLP capabilities for applications, such as tablets and smart phones, and provide solutions to overcome current FOWLP limitations.

FOWLP enables multiple chips to be integrated in small form factor on a single package. Today, this low-cost packaging technology is challenged by package and pin-count limitation of a few hundreds of I/Os on a single device package. These limitations directly impact FOWLP's capability to support the increased performance requirements and application support needed by mobile smart devices. This consortium aims to provide solutions by working together to develop a high density FOWLP test vehicle capable of overcoming those limitations.

"Besides technical challenges, cost has been a growing concern in the semiconductor industry. This consortium is looking at both the technical and cost issues of High-Density FOWLP, and driving towards a high volume manufacturing solution to hasten its adoption in the industry," said Cheam Tong Liang, Kulicke & Soffa's Vice President of the Advanced Packaging Business Line & Corporate Strategy.

"System integration is necessary to enable diverse functionalities with high performance in future applications across a wide spectrum of industries including computing and networking, healthcare, consumer electronics, transport and automotive. With the High-Density Fan-Out Wafer Level Packaging consortium, IME continues to add to its portfolio of advanced packaging platforms so as to provide wide-ranging solutions for the continued evolution and different needs of complex and demanding devices," said Prof. Dim-Lee Kwong, Executive Director of IME.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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